INTEGRATED CIRCUIT AND METHOD OF FABRICATION THEREOF

ABSTRACT

A method of forming an integrated circuit structure comprising the steps of forming a first and second device region on a surface of a wafer, forming a spacer of a first width on a sidewall of a first gate stack in the first device region, forming a spacer of a second width on a sidewall of a second gate stack in the second device region, with the first width being different from the second width.

Figure 7